PATENT Appl. No. 10/774,707 Amdt. dated March 7, 2005 Reply to Office action of Dec. 10, 2004 04-13161

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This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A thermal device for applying thermal energy to the body of a person, animal or other surface, comprising:

degermed corn grain; and

- an enclosure configured to enclose said degermed corn grain.
- 2. (original) The thermal device of Claim 1, wherein said enclosure is made from fabric.
- 3. (currently amended) The thermal device of Claim 1, wherein said degermed corn grain is kiln dried.
- 4. (currently amended) The thermal device of Claim 1, wherein said degermed corn grain is oven dried.
- 5. (original) The thermal device of Claim 1, wherein said enclosure is generally rectangular.
- 6. (currently amended) A thermal device for applying thermal energy to the body of a person, animal or other surface, comprising segmented degermed grain configured to accept thermal energy.

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7. (currently amended) A method of applying thermal energy to the body of a person, animal or other surface, comprising:

providing a thermal device including segmented degermed grain; subjecting said thermal device to thermal energy; and applying said thermal device to a surface to be treated.

- 8. (currently amended) The thermal device of Claim 7, wherein said segmented degermed grain is corn.
- 9. (cancelled)
- 10. (currently amended) The thermal device of Claim 7, wherein said segmented degermed grain is embryo-free corn.
- 11. (currently amended) The thermal device of Claim 10, wherein said degermed embryo-free corn dissipates thermal energy relatively slowly.
- 12. (currently amended) A thermal device for applying thermal energy to the body of a person, animal or other surface, comprising:

segmented-degermed organic filler; and

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a receptacle configured to enclose said segmented degermed organic filler.

- 13. (currently amended) The thermal aid of Claim 12, wherein said segmented degermed organic filler is degermed grain.
- 14. (currently amended) The thermal aid of Claim 12, wherein said segmented degermed organic filler is embryo-free grain.
- 15. (currently amended) The thermal aid of Claim 12, wherein said segmented degermed organic filler is kiln-dried grain.
- 16. (currently amended) The thermal device of Claim 12, wherein said segmented degermed organic filler is oven dried.
 - 17. (currently amended) The thermal aid of Claim 12, wherein said segmented degermed organic filler is dissected grain.
- 18. (currently amended) The thermal aid of Claim 12, wherein said segmented degermed organic filler is corn.

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- 19. (original) The thermal device of Claim 12, wherein receptacle is generally rectangular.
- 20. (currently amended) A method of making a thermal device, comprising:

providing grain;

segmenting said grain to provide degermed grain; and enclosing said segmented degermed grain in an enclosure.

- 21. (original) The method of Claim 20, wherein said segmenting comprises:
 - cleaning the grain to remove foreign material;

tempering the grain;

removing the embryo;

sifting out undesirable elements to produce a resulting grain; and

drying said resulting grain.

22. (new) The thermal device of Claim 1, wherein said degermed grain is corn.